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JAPANESE PATENT OFFICE

PATENT ABSTRACTS OF JAPAN

(11) Publication number: 10050736 A

(43) Date of publication of application: 20 . 02 . 98

(51) Int. Cl. H01L 21/52

(21) Application number: 08223212

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(22) Date of filing: 08 . 08 . 96

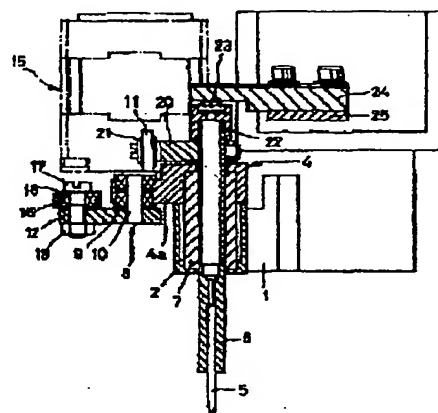
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(54) DIE BONDING HEAD OF DIE BONDER

(57) Abstract:

PROBLEM TO BE SOLVED: To enable the correction of the rotating direction of a chip and easy setting of the load in bonding.

SOLUTION: A collet holder 6 for holding a collet 5 is vertically movably and rotatably mounted on a bonding arm 1 and magnetically attracted to and hangs down from one end of a load transfer arm 25 having a loading means at the other end, thereby loading the holder 6 through the load transfer arm 25 in bonding. The bonding arm 1 has a crank pin 8 having a guide pin eccentric to a rotary shaft 10 and the collet holder 6 has a pair of rollers 21 contacted to both sides of the guide pin 11 to block it from rotating. An actuator is driven to rotate the crank pin 8 through links 12, 16 and directly rotate the holder 6 through the rotating guide pin 11.



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